



# SPECIFICATION FOR APPROVAL

CUSTOMER : \_\_\_\_\_

PRODUCT TYPE : SMD SEAM SEALING CRYSTAL 2.5\*2.0

NOMINAL FREQ. : 26.000000MHz

TXC P/N : 8Z26000006

REVISION : A1

CUSTOMER P/N : \_\_\_\_\_

PM / SALES : \_\_\_\_\_

DATE : \_\_\_\_\_

CUSTOMER SIGNATURE & Date

\_\_\_\_\_

\_\_\_\_\_

- (1) TXC requires one copy returned with signature and title of authorized individual that signifies acceptance of the attached specifications.
- (2) Orders received and accepted by TXC after return of signed copy of specification will be produced per these specifications.
- (3) Any changes to these specifications must be agreed upon by both parties and new revision of the Product Specification Sheet will be issued.
- (4) Any issuance of purchase order prior to consigning back the Approval page of "Specification Sheets" from customers will be regarded as the agreement on the contents of these specifications.

- Note :**
- 1. This specification sheet is for Infineon and TXC internal use only.
  - 2. The content of this document might not be same as the one that open published for Infineon's ULC3 crystal application.
  - 3. The specification items and criteria in this document show the actual conditions for Infineon's ULC3 crystal applications.
  - 4. Both parties agree to sign two different documents for those two different occasions.

**RoHS Compliant**



# PRODUCT SPECIFICATION SHEET

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PE/RD	QA	MFG
<i>Scott Chen</i>	<i>T.M. Yan</i>	<i>Jelly Teng</i>
<i>24-Jun-08</i>	<i>24-Jun-08</i>	<i>24-Jun-08</i>

**NOTE:**

- (1)Lead Free Products are "Directive 2002/95/EC of The European Parliament of 27 January 2003 on the restriction of the use of certain hazardous substances (RoHS) in electrical and electronic equipment" Compliant (Attachment: SGS Test Report).
- (2)Revision "Sx" is for engineering samples only. PE/RD's approval required.
- (3)Revision "Ax" is production ready. PE, QA and MFG's approval required

**RoHS Compliant**



## ELECTRICAL SPECIFICATIONS

### Standard atmospheric conditions

Unless otherwise specified, the standard range of atmospheric conditions for making measurement and tests are as follow:

Ambient temperature : 25±10  
 Relative humidity : 40%~70%

If there is any doubt about the results, measurement shall be made within the following limits:

Ambient temperature : 25±3  
 Relative humidity : 40%~70%

### Measure equipment

Electrical characteristics measured by HP E5100A or equivalent.

### Crystal cutting type

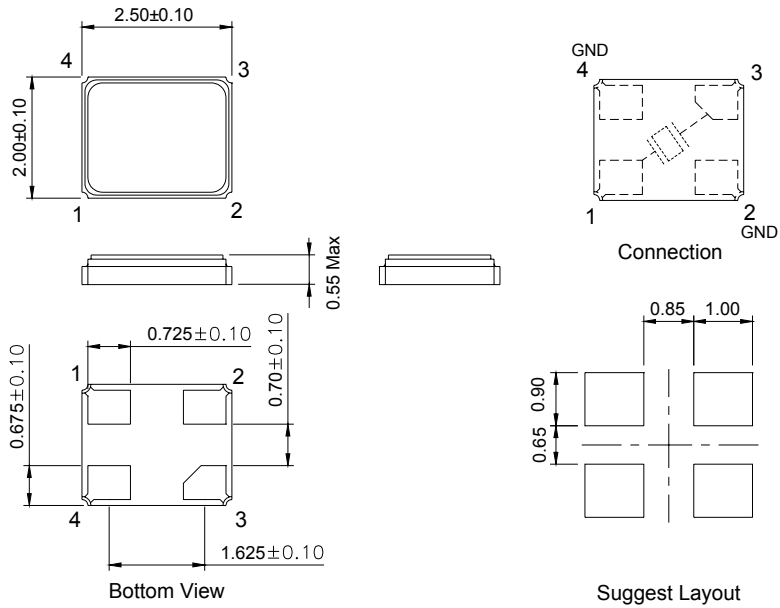
The crystal is using AT CUT (thickness shear mode).

### Unit Weight:

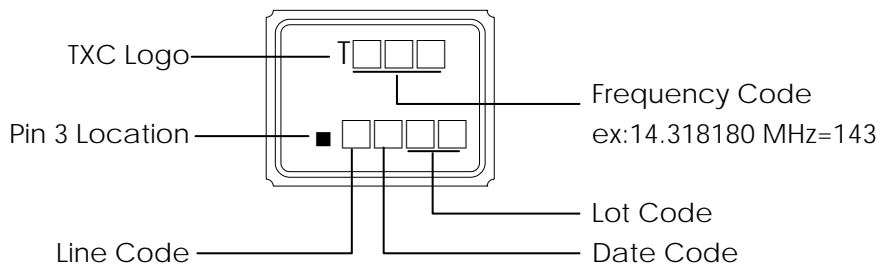
0.009±0.001 g/pcs

	Parameters	SYM.	Electrical Spec.				Notes
			MIN	TYPE	MAX	UNITS	
1	Nominal Frequency	F0	26.000000			MHz	offset: -5ppm
2	Nominal Temperature	-	24	29	34		-
3	Oscillation Mode	-	Fundamental			-	-
4	Load Capacitance	CL	8.5			pF	-
5	Frequency Tolerance	df/F	±10			ppm	T=29±5
6	Frequency Stability	df/F	±13			ppm	Over Operating Temp. Range (Reference 25 )
7	Operating Temperature	-	-30	~	85		-
8	Aging	-	±3			ppm	5 Years, T=29±5
9	Drive Level	Pd	1	-	100	uW	-
10	Effective Resistance Rr	ESR	-	-	40	Ω	-
11	Shunt Capacitance C0	C0	0.8	1.0	1.2	pF	-
12	Motional Capacitance C1	C1	2.88	3.60	4.32	fF	-
13	Insulation Resistance	IR	500	-	-	MΩ	at DC 100V
14	Storage Temperature Range	-	-40	~	85		-
15	Frequency discontinuities	dips	±1			ppm	-
16	Relative series resistance of unwanted modes $a_{NW}=20 \cdot \log (R_{NW}/R_r)$	$a_{NW}$	6	-	-	dB	-

**DIMENSIONS**



**MARKING**



**Date Code:**

YEAR		MONTH													
		JAN	FEB	MAR	APR	MAY	JUN	JUL	AUG	SEP	OCT	NOV	DEC		
2005	2009	2013	2017	A	B	C	D	E	F	G	H	J	K	L	M
2006	2010	2014	2018	N	P	Q	R	S	T	U	V	W	X	Y	Z
2007	2011	2015	2019	a	b	c	d	e	f	g	h	j	k	l	m
2008	2012	2016	2020	n	p	q	r	s	t	u	v	w	x	y	z

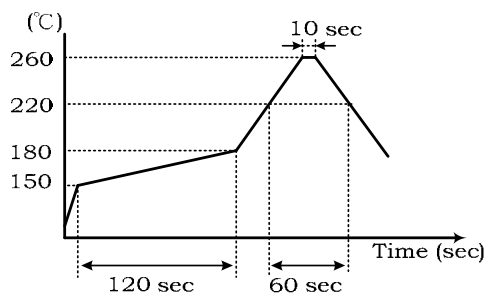
\*This date code will be cycled every four years

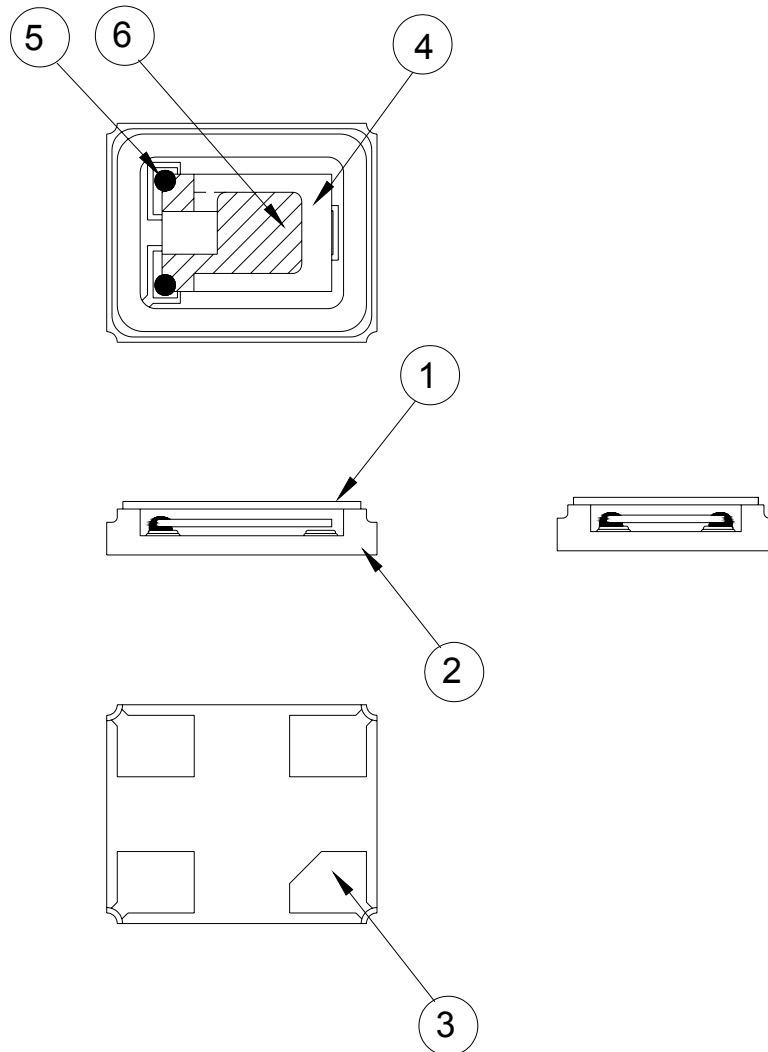
**Production location: Taiwan**

**SUGGESTED REFLOW PROFILE**

Total time : 200 sec. Max.

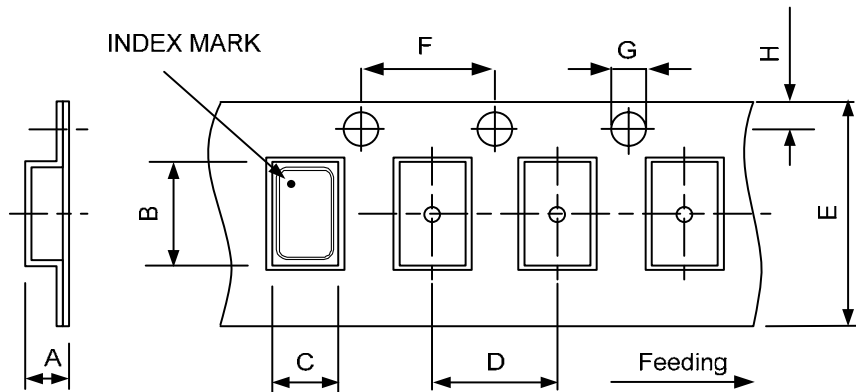
Solder melting point :220



**STRUCTURE ILLUSTRATION**


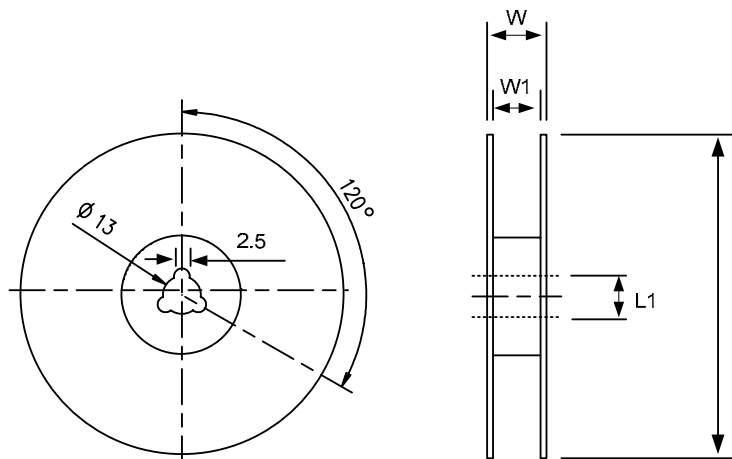
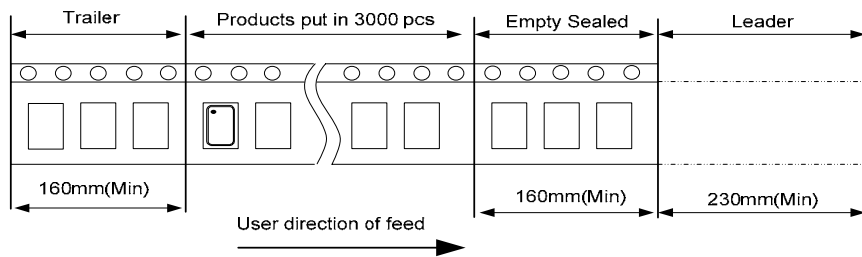
NO	COMPONENTS	MATERIALS	FINISH/SPECIFICATIONS
1	Lid	Kovar (Fe/Co/Ni)	-
2	Base(Package)	Ceramic (Al <sub>2</sub> O <sub>3</sub> ) + Kovar (Fe/Co/Ni)+ Ag/Cu	Alumina ceramics
3	PAD	Au	Tungsten metalize + Ni plating + Au plating
4	Crystal blank	SiO <sub>2</sub>	-
5	Conductive adhesive	Ag	Silicone resin
6	Electrode	Noble Metal	-

**PACKING**



DIMENSIONS	A	B	C	D	E	F	G	H	(UNIT : mm)
	1.05	2.7	2.25	4	8	4	1.55	1.75	

**REMARK :**



DIMENSIONS	L	L1	W	W1	pcs / Reel (UNIT : mm)
	178	13	11.5	8	Standard Reel Quantity is 3,000 pcs per reel

## RELIABILITY SPECIFICATIONS

### 1. Mechanical Endurance

No.	Test Item	Test Methods	REF.DOC
1.1	Drop Test	150 cm height, 3 times on concrete floor.	JIS C6701
1.2	Mechanical Shock	Device are shocked to half sine wave ( 1000 G ) three mutually perpendicular axes each 3 times. 0.5m sec. duration time	MIL-STD-202
1.3	Vibration	Frequency range 10 ~ 2000 Hz Amplitude 1.52 mm/20G Sweep time 20 minute perpendicular axes each test time 4 hours (Total test time 12 hours)	MIL-STD-883
1.4	Gross Leak	Standard Sample For Automatic Gross Leak Detector, Test Pressure: 2Kg / cm <sup>2</sup>	MIL-STD-883
1.5	Fine Leak	Helium Bombing 4.5 Kg/ cm <sup>2</sup> for 2 hr	
1.6	Solder ability	Temperature 245 ± 5 Immersing depth 0.5 mm minimum Immersion time 5 ± 1 seconds Flux Rosin resin methyl alcohol solvent ( 1 : 4 )	MIL-STD-883

### 2. Environmental Endurance

No.	Test Item	Test Methods	REF. DOC
2.1	Resistance To Soldering Heat	Pre-heat temperature 125 Pre-heat time 60 ~ 120 sec. Test temperature 260 ± 5 Test time 10 ± 1 sec.	MIL-STD-202
2.2	High Temp. Storage	+ 125 ± 3 for 500 ± 12 hours	MIL-STD-883
2.3	Low Temp. Storage	- 40 ± 3 for 500 ± 12 hours	
2.4	Thermal Shock	Total 100 cycles of the following temperature cycle 	MIL-STD-883
2.5	High Temp & Humidity	85 ± 3 , RH 85% , 500Hrs	JIS C5023
2.6	Pressure Cooker Storage	121 ± 3 , RH100% , 2 bar , 240Hrs	JIS C6701